



02/22/02

Docket No. 5853-224

## PATENT APPLICATION TRANSMITTAL LETTER

Commissioner for Patents  
**BOX PATENT APPLICATION**  
 Washington, DC 20231

Transmitted herewith for filing of the patent application of:

Inventor(s): Rajiv K. Singh  
 Seung-Mahn Lee



for **SLURRY AND METHOD FOR CHEMICAL MECHANICAL POLISHING OF METAL STRUCTURES INCLUDING REFRACTORY METAL BASED BARRIER LAYERS**

are the following:

- ☒ Specification, including Abstract  
☒ 10 Sheets of drawing (3 sets)  
☒ Executed Declaration and Power of Attorney  
☒ Assignment with Recordation Cover Sheet  
☒ Other: 2 postcards

## CLAIMS AS FILED

FOR	NO. FILED	NO. EXTRA
Basic Fee		
Total Claims	71	51
Indep Claims	6	3
multiple dependent claim present No		

If the difference in Col. 1 is less than zero, enter "0" in Col. 2  
 Assignment Recordation

## Small Entity

RATE	FEE
	\$ 370.00
x \$ 9 =	\$ 459.00
x \$ 42 =	\$ 126.00
x \$ 135 =	\$
TOTAL	\$ 955.00
	\$ 40.00

## Other than a Small Entity

RATE	FEE
	\$ 740.00
x \$ 18 =	\$
x \$ 84 =	\$
x \$ 270 =	\$
TOTAL	\$

- ☒ You are hereby authorized to charge \$995.00 to Deposit Account 50-0951.  
☒ The Commissioner is hereby authorized to charge any underpayment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 50-0951.  
 A duplicate of this sheet is enclosed.  
☒ Any additional filing fees required under 37 C.F.R. 1.16.  
☒ Any patent application processing fees under 37 C.F.R. 1.17.

Date

Neil R. Jetter

Registration No. 46,803